

CMF2K Series



High Current Common Mode Choke



FEATURES

- Surface mountable (multiple case sizes), high current common mode choke for DC power line
- Base terminals are treated, allows for easy mounting on PCB
- Paired wire coil for high stability
- Optimized for transmission of high quality signals
- Operating temperature: -40 °C to +125 °C
- Rated Current: Based on temp. rise; ∆T: 40 °C, typical
- Material categorization: For definitions of compliance please see

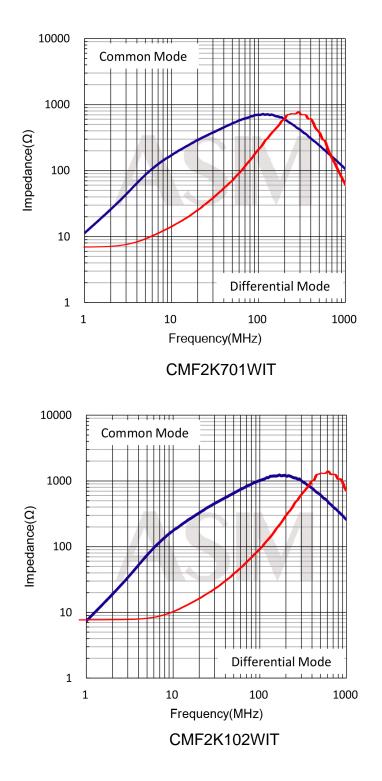
APPLICATIONS

- LAN's, telephones, personal computers
- CD-ROM drives, electronic games
- Other electronic devices

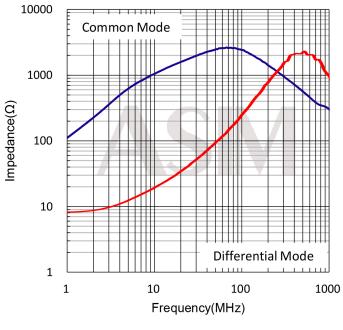
STANDARD ELECTRICAL SPECIFICATIONS						
PART NUMBER	COMMON MODE IMPEDANCE AT 100 MHz (Ω)	RATED VOLTAGE MAX. (V _{DC})	RATED CURRENT MAX. (mA)	DC RESISTANCE MAX. (Ω)	INSULATION RESISTANCE MIN. (MΩ)	
CMF2K701WIT	700±25%	50	5000	0.010	10	
CMF2K102WIT	1000±25%	50	4000	0.013	10	
CMF2K272WIT	2700±25%	50	2000	0.086	10	



PERFORMANCE GRAPHS: INDUCTANCE AND Q VS. FREQUENCY

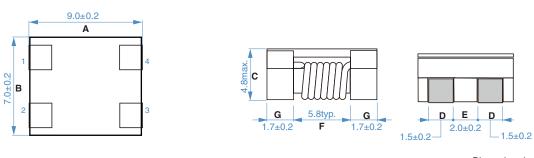




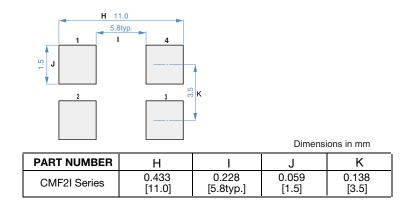


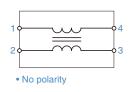
CMF2K272WIT

DIMENSIONS in inches [millimeters]



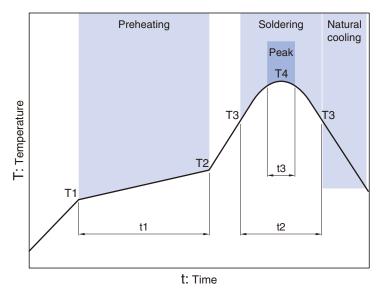
							Dimensions in mm
PART NUMBER	А	В	С	D	Е	F	G
CMF2K Series	$\begin{array}{c} 0.354 \pm 0.008 \\ [9.0 \pm 0.2] \end{array}$	$\begin{array}{c} 0.276 \pm 0.008 \\ [7.0 \pm 0.2] \end{array}$	0.189 [4.8] max.		$\begin{array}{c} 0.079 \pm 0.008 \\ [2.0 \pm 0.2] \end{array}$	0.228 [5.8] typ.	0.059 ± 0.008 [1.7 ± 0.2]







RECOMMENDED REFLOW PROFILE



Preheating Soldering Peak Temp. Time Temp. Time Temp. Time T2 T1 t1 Т3 t2 **T**4 t3 150°C 180°C 60 to 120s 230°C 25 to 35s 250°C 5s

RELIABLITY TEST METHOD

• ELECTRIC

NO.	Test items	Standard	Experiment Method
1	Temperature characteristics	ΔL/L 20°C ≤ ±10%	The test should be done after the sample has stabilized in the ring The temperature of the product is -40 to +125 °C, and the L (Δ L) value of the product is the same as the original L value. Suitable for normal temperature and humidity should be Δ L / L 20 ° C ≤ ± 10 %.
2	Load test	The product must not have any damage, such as smoke or sparks	1.2 times the rated current, the time is 5 minutes



6.2 ENVIRONMENTAL CHARACTERISTICS

NO.	Test items	Standard	Experiment Method	
1	Reflow soldering	Do not have any damage or problems	Reflow of temperature distribution Before the heat: 150-180 °C, Times 60 to 120sec Peak temperature: 250 \pm 5 °C, Times 5 sec Hold temperature: 230 \pm 5 °C, Times 30 \pm 5 sec $\frac{250 \pm 5 ^{\circ}C}{930 ^{\circ}C}$	
2	Solderability		The solder surface is immersed in flux and then immersed in a furnace at 235 \pm 5 $^\circ C$ for 5 seconds	
3	Low temperature storage	there should be no	The sample should be left for 96 \pm 4 hours at a temperature of -40 \pm 3 °C and returned to the normal temperature range of 1 hour after completion of the test.) 90-95%.	
4	High temperature storage	there should be no	The sample should be left for 96 \pm 4 hours at a temperature of 125 \pm 3 °C. The test should be carried out after returning to normal temperature range for 1 hour.	
5	Constant hot and humid	there should be no	5 ()	
6	Temperature cycle	1, no visible mechanical damage. 2, the value of change is less than 10%. 3, the resistance value of less than 5%	In the -25 °C to +85 °C between the respective keep 15min, transit time ≤1min, the number of cycles 5 times, recovery time: 24h test finished (recovery time at least 4h)	
7	vibration	There should be no mechanical damage	The sample should be soldered to the printed circuit board When the vibration has an amplitude and 1.5 mm Frequency from 10-55Hz / 1 minute, repeated should be applied to three directions (X, Y, Z) for 2 hours, a total of 6 hours	
8	Impact resistance (MIL-STD-202G Method 213B)	DC resistance change: ± 10% within the appearance of no obvious	Acceleration 980 m/s ⁻ (100g) Nominal pulse duration 6 ms Speed change 3.75 m/s	



		inductance: within ± 10%	The test sample shall be soldered to the test substrate by reflow soldering. Test sample according to the specified time Are placed at a specific temperature, as shown in the table below, from step 1 to step 4.			
	Thermal shock (MIL-STD-202G	DC resistance	1 cycle condition			
9		change: ± 10% within	1 - 55 + 3 - 30 + 3			
5	Method 107G)	the appearance of no	2 Room temperature 3 or less			
		obvious	3 -125±3 30±3			
		abnormalities, should	4 Room temperature 3 or less			
		not have mechanical damage.	Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.			
Wet heat resistance	Change in inductance: within ± 10% DC resistance change: ± 10% within	The test sample shall be soldered to the test substrate by reflow soldering. Test samples must be placed in a constant temperature and humidity box, according to the table specified temperature and humidity, do not pass the current test.				
10	(MIL-STD-202G	the appearance of no	Humidity 90%±10%RH			
	Method 106G)	obvious	Time 500±24 hours			
	abnormalities, should not have mechanical damage.					
11	Low temperature life (IEC68-2-1Ad)	Change in inductance: within ± 10% DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.	Time 500±24 hours			
12	Low temperature load life (IEC68-2-1Ad)	Change in inductance: within ± 10% DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical	1000 ± 24 nours			
		damage.	The test sample shall be soldered to the test substrate by reflow			
13	Damp heat load (MIL-STD-202G Method 108A)	inductance: within ± 10% DC resistance change: ± 10% within the appearance of no obvious abnormalities, should	soldering. Test samples shall be placed in a constant temperature and humidity box, according to the table specified in the temperature and humidity under the continuous access to the rated current for testing. <u>Temperature 60±2°C</u> <u>Humidity 90~95%RH</u> <u>Time 500+24 hours</u>			
		Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.				



14	High temperature life test (IEC68-2-2Ba)	DC resistance change: ± 10% within the appearance of no obvious	The test sample shall be soldered to the test substrate by reflow soldering. The test sample shall be placed in a constant temperature and humidity tank and the current shall not be supplied at the temperature specified in the table. Temperature 125±3°C Time 500±24 hours Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.
15	High temperature load life test (MIL-STD-202G Method 108A)	10% DC resistance change: ± 10% within the appearance of no obvious	Ime 2000±24 nours Hourly power time 3/4 power Hourly power time 3/4 power Recovery: 2 hours of recovery in standard condition and power to the standard condition and power